



Material Content Data Sheet



Sales Product Name				IPZ40N04S5L-4R8		Issued		31. January 2019	
MA#				MA001338258					
Package				PG-TSDSON-8-32		Weight*		35.35 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.336	0.95	0.95	9491	9491	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88		
	non noble metal	zinc	7440-66-6	0.012	0.04		352		
	non noble metal	iron	7439-89-6	0.249	0.70		7038		
wire	non noble metal	copper	7440-50-8	10.102	28.58	29.33	285758	293236	
	noble metal	gold	7440-57-5	0.030	0.09	0.09	861	861	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1054	
	plastics	epoxy resin	-	1.918	5.43		54255		
	inorganic material	silicondioxide	60676-86-0	16.667	47.12	52.66	471442	526751	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11322	11322	
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2422	2422	
solder	non noble metal	tin	7440-31-5	0.010	0.03		294		
	noble metal	silver	7440-22-4	0.013	0.04		367		
	non noble metal	lead	7439-92-1	0.496	1.40	1.47	14035	14696	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17		
	non noble metal	zinc	7440-66-6	0.002	0.01		66		
	non noble metal	iron	7439-89-6	0.047	0.13		1329		
heat sink CLIP	non noble metal	copper	7440-50-8	1.908	5.40	5.54	53960	55372	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
	non noble metal	iron	7439-89-6	0.073	0.21		2060		
	non noble metal	copper	7440-50-8	2.958	8.37	8.59	83660	85849	
	*deviation	< 10%				Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com